PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
JM38510/10901BPA	ACTIVE	CDIP	JG	8	50	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	JM38510 /10901BPA	Samples
NA555D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 105	NA555	
NA555DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 105	NA555	Samples
NA555P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU | SN	N / A for Pkg Type	-40 to 105	NA555P	Samples
NA555PE4	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 105	NA555P	Samples
NE555D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	NE555	
NE555DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	0 to 70	NE555	Samples
NE555DR1G4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	NE555	Samples
NE555DRG4	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	0 to 70	NE555	
NE555P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU | SN	N / A for Pkg Type	0 to 70	NE555P	Samples
NE555PE4	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	0 to 70	NE555P	Samples
NE555PS	ACTIVE	SO	PS	8	80	RoHS & Green	NIPDAU	Level-1-260C-UNLIM		N555	Samples
NE555PSR	ACTIVE	SO	PS	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	N555	Samples
NE555PW	OBSOLETE	TSSOP	PW	8		TBD	Call TI	Call TI	0 to 70	N555	
NE555PWR	ACTIVE	TSSOP	PW	8	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	N555	Samples
SA555D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85	SA555	
SA555DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU | SN	Level-1-260C-UNLIM	-40 to 85	SA555	Samples
SA555DRG4	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-40 to 85	SA555	
SA555P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	-40 to 85	SA555P	Samples
SE555D	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-55 to 125	SE555	
SE555DG4	OBSOLETE	SOIC	D	8		TBD	Call TI	Call TI	-55 to 125	SE555	
SE555DR	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SE555	Samples

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SE555DRG4	ACTIVE	SOIC	D	8	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-55 to 125	SE555	Samples
SE555FKB	ACTIVE	LCCC	FK	20	55	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SE555FKB	Samples
SE555JG	ACTIVE	CDIP	JG	8	50	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SE555JG	Samples
SE555JGB	ACTIVE	CDIP	JG	8	50	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	SE555JGB	Samples
SE555P	ACTIVE	PDIP	P	8	50	RoHS & Green	NIPDAU	N / A for Pkg Type	-55 to 125	SE555P	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals.
TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SE555, SE555M :

- Catalog : SE555
- Military : SE555M
- Space : SE555-SP, SE555-SP

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications
- Space - Radiation tolerant, ceramic packaging and qualified for use in Space-based application